

Abstract

Method for grinding semiconductor wafers

5 A method of grinding a semiconductor wafer, wherein the semiconductor wafer
is machined to remove material by means of a grinding tool comprising grinding
teeth having a height h while supplying a cooling medium into a contact region
between the rotating semiconductor wafer and the grinding tool, wherein at each
instant of grinding a first coolant flow is applied to a first region on one side of the
semiconductor wafer by means of one or more nozzles and wherein at each
10 instant of grinding a second coolant flow is applied to a second region on the one
side of the semiconductor wafer by means of one or more nozzles, characterized
in that the first region is bounded by the lower right quadrant of the semiconductor
wafer and the second region is bounded by the lower left quadrant, and the
quotient of the first coolant flow and the sum of the first and second coolant flows
15 is not greater than 35% and not less than 25%.

Drawing for the Abstract: Figure 2